

ABSTRACT

A plasma processing apparatus and a focus ring enables
to perform uniform plasma processing over the entire surface
5 of a substrate to be processed to thereby improve in-surface
uniformity of plasma processing compared with conventional
cases. The focus ring is disposed on a susceptor 2, which
serves to mount thereon a semiconductor wafer W and further
functions as a lower electrode, to surround a periphery of
10 the semiconductor wafer W. The focus ring 6 includes a ring
member of a thin plate shape disposed to surround the
periphery of the wafer W while maintaining a gap
therebetween and a lower ring body installed below the
semiconductor wafer and the ring member of the thin plate
15 shape.